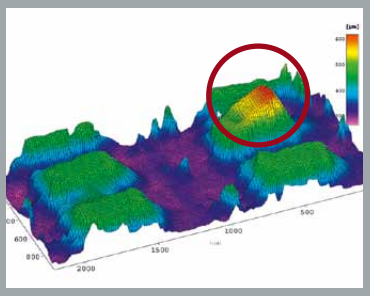
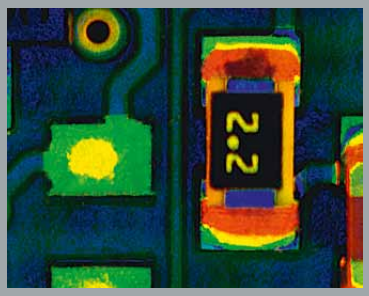
VISCOM
vision technology

XM Sensor Technology



Tombstone in 3-D view



Reliable classification and simple verification through color illumination

Fast, flexible, powerful

With the XM technology, Viscom has taken another major step in the development of camera modules. With an image capture rate of up to 1.8 gigapixel/sec, the new XM module is one of the fastest AOI camera systems on the market. The XM module is a completely proprietary development from Viscom, combining more than 25 years' experience in inspection technology.

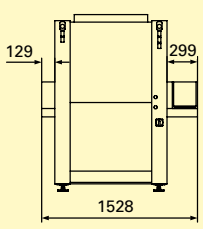
The four-color illumination from all spatial directions achieves optimum contrast for all recognizable solder defects as well as for special features such as script, polarity marks or colored components. The high performance module works with switchable optical resolution of 16 or 8 µm and can handle the most extreme throughput requirements. Extension of the angled view, capture of additional images for the verification station, and additional illuminations are nearly cycle time-neutral. This increases the inspection depth and first-pass yield. Additional options such as full 3-D measurement or color gradient analyses also are available.

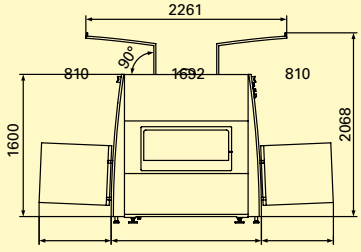
Of course, the XM module commands the typical Viscom angled view. The new camera technology is available for the S6056 as of now. Viscom customers benefit from the 8M compatibility mode. This function guarantees an easy transfer of already existing inspection patterns and complete libraries.

AOI

Technical Specifications

	S6056 XM ST1W	S6056 XM DS1W
Transport system	Single track	Dual track
Inspection concept	Single inspection	Single inspection
Application		
	Solder joint, assembly, solder paste	
Camera technology		
Orthogonal camera module XM		
Field of view	40 x 40 mm (1.57" x 1.57")	
Resolution	16 µm (standard), 8 µm (high) switchable with OnDemandHR	
Number of mega pixel cameras	1	
Angled view camera module XM		
Resolution	16 µm (standard)	
Number of mega pixel cameras	4/8 (optional)	
Software		
User interface	Viscom EasyPro/EasyAuto/ViscomVisionPilot (VVP)	
Verification station	Viscom HARAN (optional)	
SPC	Viscom SPC (statistical process control), open interface (optional)	
Remote diagnosis	Viscom SRC (optional)	
Off-line programming	Viscom PST34 (external Programming Station) (optional)	
System computer		
Operating system	Windows®	
Processor	Intel® Core™ i7	
PCB handling		
PCB dimensions (L x W)	457 x 356 mm (17.9" x 14.0") (Specification of the DS1W version, other sizes optional)	
PCB carrier	1 - 5 mm (0.04" - 0.2") (lower thicknesses optional)	
Transport height	850 to 960 mm ± 20 mm (33.5" to 37.8" ± 0.8")	
Width adjustment	Automatically with set-up	
Handling unit	Linear motors	
PCB clamping	Pneumatic during inspection	
PCB contact area	3 mm (0.1")	
Upper transport clearance	50 mm (1.9")	
Lower transport clearance	40 mm (1.6") (other heights upon request)	
Inspection speed		
	40 - 60 cm^2/s, no handling time	
Other system data		
Interfaces	SMEMA, SV70, customer specific	
Power requirements	300~400 V, 50/60 Hz, < 3 kW, 6 bar compressed air	
Line gap requirements	System width approx. +30 mm (1.2")	
System dimensions (W x D x H)	1528 x 1692 x 1650 mm (60.2" x 66.7" x 65.0")	
Weight (max.)	Approx. 1450 kg (3197 lbs)	





Sideview with open doors

Dimensions in mm

Headquarters:

Viscom AG
Carl-Buderus-Str. 9 - 15 · 30455 Hanover · Germany
Tel.: +49 511 94996-0 · Fax: +49 511 94996-900
info@viscom.com · www.viscom.com

Visit our website to find international subsidiaries and representatives in Europe, USA and Asia:

www.viscom.com

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